

### SSC8336GQ4

### **Dual Asymmetric N-Channel Enhancement Mode MOSFET**

#### > Features

VDS	VGS	RDSON Typ.	ID
201/	±20V	13mR@10V	
30V		17mR@4V5	12A

## > Description

This device uses advanced trench technology to provide excellent RDSON and low gate charge. This device is suitable for use as a load switch or in PWM applications.

## Applications

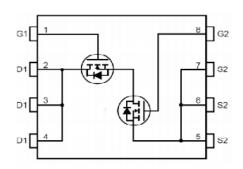
- Power Management in notebook computer
- Portable Equipment
- Battery Powered Systems

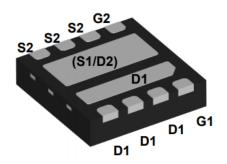
### Ordering Information

Device	Package	Shipping	
SSC8336GQ4	DFN3X3	5000/Reel	

# > Pin configuration

Top view





**Bottom View** 



(Y: year/W: week)

Marking



# ➤ Absolute Maximum Ratings(T<sub>A</sub>=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Unit	
V <sub>DSS</sub>	Drain-to-Source Volt	30	V	
$V_{GSS}$	Gate-to-Source Volt	age	±20	V
,	Cartinua Daria Camant	TC=25°C	12	Α
I <sub>D</sub>	Continuous Drain Current	TC=100°C	9	Α
I <sub>DM</sub>	Pulsed Drain Curre	nt <sup>b</sup>	36	Α
I <sub>DSM</sub>	Continuous Drain Current <sup>a</sup>	TA=25°C	10	Α
		TA=70°C	8	А
P <sub>D</sub>	Power Dissipation °	TC=25°C	20	W
		TC=100°C	8	W
Б	D D: : :: :	TA=25°C	2.5	W
$P_{DSM}$	Power Dissipation <sup>a</sup>	TA=70°C	0.9	W
I <sub>AS</sub>	Avalanche Currer	20	Α	
E <sub>AS</sub>	Avalanche Energy, L=0.1mH		20	mJ
TJ	Operation junction temp	-55 to 150	°C	
T <sub>STG</sub>	Storage temperature	-55 to 150	°C	

### $\rightarrow$ Thermal Resistance Ratings(T<sub>A</sub>=25°C unless otherwise noted)

Symbol	Parameter	Typical	Maximum	Unit
R <sub>θJA</sub>	Junction-to-Ambient Thermal Resistance <sup>a</sup>		55	°C /\\/
Rejc	Junction-to-Case Thermal Resistance		6.5	°C/W

#### Note:

- a. The value of RθJA is measured with the device mounted on 1 in² FR-4 board with 2oz.copper,in a still air environment with TA=25°C. The value in any given application depends on the user is specific board design. The current rating is based on the t≤10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation PD is based on TJ(MAX)=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

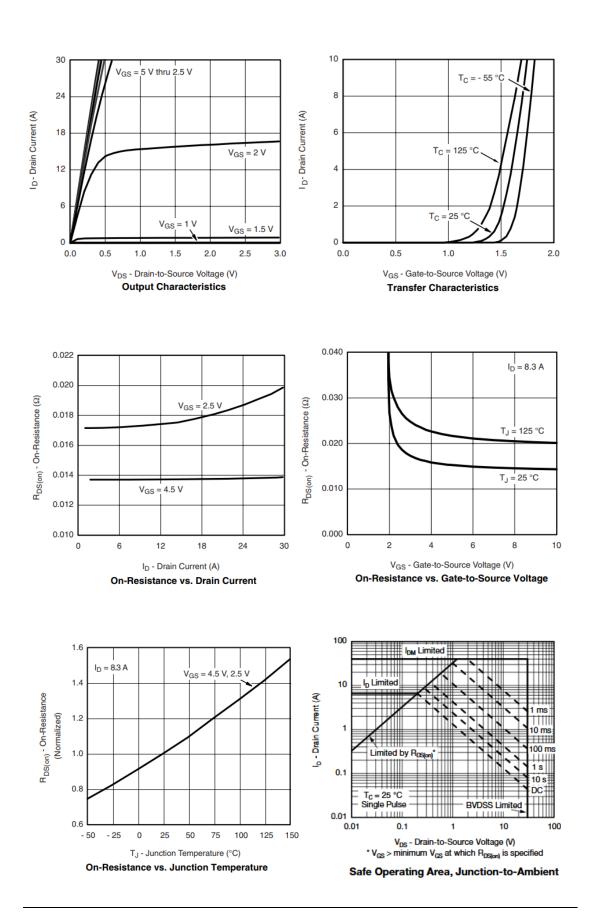


# ightharpoonup **Electronics Characteristics**(T<sub>A</sub>=25 $^{\circ}$ C unless otherwise noted)

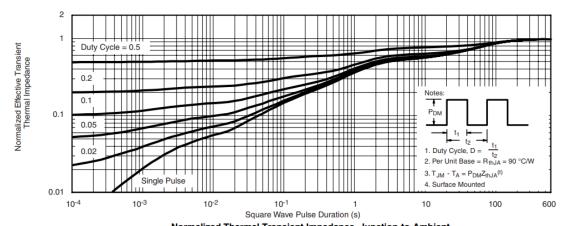
Symbol	Parameter	Test Conditions	Min	Тур.	Max	Unit
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	VGS=0V,ID=250uA	30			V
V <sub>GS (th)</sub>	Gate Threshold Voltage	VDS=VGS,ID=250uA	1.1	1.7	2.1	V
	Drain-Source On-	VGS=10V,ID=9A		13	18	
R <sub>DS(on)</sub>	Resistance	VGS=4.5V,ID=7.5A		17	24	mR
I <sub>DSS</sub>	Zero Gate Voltage  Drain Current	VDS=24V,VGS=0V			1	uA
I <sub>GSS</sub>	Gate-Source leak	VGS=±20V,VDS=0V			±100	nA
V <sub>SD</sub>	Forward Voltage	VGS=0V,IS=0.5A		0.8	1.3	V
G <sub>FS</sub>	Transconductance	VDS=15V,ID=10A		20		S
Ciss	Input Capacitance			530		
Coss	Output Capacitance	VDS=15V, VGS=0V, f=1MHz		200		pF
Crss	Reverse Transfer Capacitance			105		
$T_{D(ON)}$	Turn-on delay time			14		
Tr	Rise time	VGS=10V,		11		no
T <sub>D(OFF)</sub>	Turn-off delay time	VDS=15V, RG=3R,RL=2.3R		15		ns
Tf	Fall time			8		
Qg	Total Gate charge			17		
Qgs	Gate to Source	VGS=10V, VDS=15V, ID=13A		2.7		nC
Qgd	Gate to Drain charge			3.7		



# ➤ Typical Characteristics(T<sub>A</sub>=25°C unless otherwise noted)



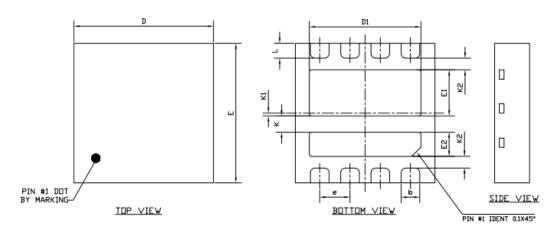


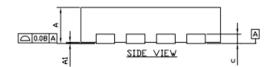


Normalized Thermal Transient Impedance, Junction-to-Ambient



# Package Information





DFN3X3

CVADDI C	SYMBOLS DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
STMBULS	MIN	NDM	MAX	MIN	NDM	MAX
Α	0.70	0.75	0.80	0.028	0.030	0.032
A1	0.00		0.05	0.000		0.002
С		0.203 REF			0.008 REF	
b	0.35	0.40	0.45	0.014	0.016	0.018
D	2.90	3.00	3.10	0.114	0.118	0.122
D1	2.30	2.40	2.50	0.090	0.094	0.098
Ε	2.90	3.00	3.10	0.114	0.118	0.122
E1	0.89	0.99	1.09	0.035	0.039	0.043
E2	0.42	0.52	0.62	0.016	0.020	0.024
е	0.65 BSC			0.026 BSC		
L	0.27	0.32	0.37	0.011	0.013	0.015
K	0.35 REF.				0.014 REF	
K1	0.06 REF.			0.002 REF.		
К2	0.25 REF.				0.010 REF	



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